

### Scope

The INFOS conference is a prestigious biennial event which brings together electrical engineers, technologists, materials scientists, device physicists and chemists from Europe and around the world to debate the newest developments on thin insulating films on semiconductors and identify the challenges ahead in this highly diversifying field.

### Conference topics

- Physics, chemistry and processing technologies of dielectrics
- Simulation and modeling of dielectrics, interfaces, 2D materials and thin films
- Characterization and reliability of dielectrics, interfaces, 2D materials and thin films
- Gate stack for advanced logic technologies
- Dielectrics for interconnects, MIM and 3D integration
- Dielectrics for high mobility substrates
- Dielectrics for 2D materials
- Advanced transistor architectures and relevant dielectrics
- Materials for conventional and emerging memories
- Materials for neuromorphic and in-memory computing
- Cryogenic electronics and quantum computing
- Ferroelectrics, functional oxides and topological insulators
- Dielectrics and thin film materials for TFTs, amorphous or organic devices
- Innovating devices with advanced insulators
- Materials for power devices
- Materials for high-frequency devices
- Materials for sensors and bioelectronics
- Materials for integrated photonics and photovoltaics

### Steering Committee

- V. Afanasiev - University of Leuven (Belgium)
- S. Cristoloveanu - IMEP (France)
- F. Crupi - University of Calabria (Italy)
- A. Dimoulas - NCSR Demokritos (Greece)
- B. Majkusiak - Warsaw University of Technology (Poland)
- J. Robertson - University of Cambridge (Great Britain)
- L. Selmi – University of Modena and Reggio Emilia (Italy)

### Local Organizing Committee

- F. Crupi (General Chair) - University of Calabria
- R. De Rose (General Co-Chair) - University of Calabria

### Submission deadlines

2-page camera ready abstracts:  
**January 16, 2023 (23:59 Pacific Time)**

4-page papers for the SSE special issue:  
**March 27, 2023 (23:59 Pacific Time)**

website: <http://events.dimes.unical.it/infos2023>

email: [infos2023@dimes.unical.it](mailto:infos2023@dimes.unical.it)

### Technical Program Committee

- M.A. Alam, Purdue University (USA)
- T. Ando, IBM (USA)
- C. Dubourdieu, Helmholtz Zentrum Berlin (Germany)
- J. Franco, imec (Belgium)
- F. Gamiz, University of Granada (Spain)
- P. Hurley, Tyndall National Institute (Ireland)
- D. Ielmini, Politecnico di Milano (Italy)
- H. Iwai, University of Tokyo (Japan)
- H.D. Kim, Sejong University (Korea)
- K. Kita, University of Tokyo (Japan)
- C. Leroux, CEA-LETI Grenoble (France)
- M. Nafria, Universitat Autònoma of Barcelona (Spain)
- L. Pantisano, Intel (USA)
- K. L. Pey, SUTD (Singapore)
- S. Slesazek, Namlab (Germany)

4-page versions of all accepted abstracts will be considered for publication in an open special issue of *Solid-State Electronics* “Letters from Insulating Films on Semiconductors 2023”. Authors of selected accepted INFOS2023 papers will be invited to submit full-length (7-10 pages) papers which will be published in another special issue of *Solid-State Electronics* “Selected papers from Insulating Films on Semiconductors 2023”.

The **Best Student Paper Award** will be delivered at the end of the conference.

